Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	154	(((((transfer adj molding) and needle) and dispenser) and encapsulant) ((((((438/118,127) or (257/737,738,782,783,787)). CCLS.) and @ad<"20020722") not micron.as.)) and @pd>"20040608"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 13:18
S2	4	(("5196371") or ("6658314") or ("20040165362") or ("20040142058")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/11/05 08:40
S3	7	(("6017776") or ("6048755") or ("6049129") or ("6177723") or ("6214645") or ("6246124") or ("6329224")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/02 13:14
S4	5489	((438/118,127) or (257/737,738, 782,783,787)).CCLS.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 10:57
S5	5007	(((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 10:59
S6	4634	((((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722") not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S7	4829	"chip scale package" CSP	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00
S8	2900	solder adj mask	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00
S9	231	("chip scale package" CSP) and (solder adj mask)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 10:59
S10	2763	"chip scale package" CSP	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:00
S11	1023	solder adj mask	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:00
S12	549	(((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and ("chip scale package" CSP)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:53
S13	342	(((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and (solder adj mask)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00

S14	18	("chip scale package" CSP) and (solder adj mask)	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:02
S15	6	"888674"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:03
S16	1	("6486005").PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 11:05
S17	27	((grigg-ford-b grigg-ford reeder-william-j reeder-william).in.) not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:05
S18	59	(grigg-ford-b grigg-ford reeder-william-j reeder-william).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:08
S19	29	(("5173220") or ("5259793") or ("5264061") or ("5278442") or ("5336931") or ("5484314") or ("5574310") or ("5705117") or ("5714800") or ("5714802") or ("5719440") or ("5767443") or ("5793116") or ("5834830") or ("5866949") or ("5920118") or ("5965933") or ("5977640") or ("5994166") or ("5999413") or ("6013946") or ("6091140") or ("6124407") or ("6222263") or ("6239013") or ("6300165") or ("6372552") or ("6448664") or ("6489183")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 11:08
S20	200	(("chip scale package" CSP) and (solder adj mask)) and @ad<"20020722"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:12
S21	188	((("chip scale package" CSP) and (solder adj mask)) and @ad<"20020722") not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:12
S22	828	((((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and ("chip scale package" CSP)) ((((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and (solder adj mask))	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:15
S23	0	(asamura-kiyoshi).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:20
S24	61	(yaguchi-akihiro).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:20

S25	0	"semiconductor adj device".ti.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:21
S26	55	"semiconductor device".ti. and ((yaguchi-akihiro).in.)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:21
S27	46	("semiconductor device".ti. and ((yaguchi-akihiro).in.)) and (kitano-makoto).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S28	6	(("semiconductor device".ti. and ((yaguchi-akihiro).in.)) and (kitano-makoto).in.) and (kumazawa-tetsuo).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S29	48	((yaguchi-akihiro).in.) and (kitano-makoto).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S30	7	(((yaguchi-akihiro).in.) and (kitano-makoto).in.) and (kumazawa-tetsuo).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S31	0	"97/10865"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:23
S32	1	"97/01865"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:52

S33	68	(("3838984") or ("5045921") or ("5409865") or ("5420460") or ("5600180") or ("5604379") or ("5608265") or ("5616958") or ("5640047") or ("5650593") or ("5656863") or ("5663593") or ("5663594") or ("5672912") or ("5859475") or ("5270267") or ("5677566") or ("5715593") or ("5785538") or ("5821605") or ("5863805") or ("5879964") or ("5880520") or ("5900582") or ("5904500") or ("5907186") or ("5929514") or ("5933708") or ("5951804") or ("5998865") or ("6013109") or ("6013535") or ("6020692") or ("6028356") or ("6107683") or ("6127833") or ("6143581") or ("6166443") or ("6169329") or ("6204093") or ("6210992") or ("5849608") or ("5920118") or ("6181569") or ("6287893") or ("6326698") or ("6376279") or ("6165885") or ("6245594") or ("6426241") or ("6284566") or ("6359221") or ("6441483") or ("6465734") or ("6475629") or ("6507107") or ("6514847") or ("6538309") or ("6555923") or ("6573612") or ("6577004") or ("6590297") or ("6671951") or ("6432746") or ("6577015") or ("6630730") or ("6653173") or ("6664139")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 13:59
S34	516	encapsulation and "solder mask"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:53
S35	443	(encapsulation and "solder mask") and @ad<"20020722" not micron. as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:53
S36	65	encapsulation with "solder mask"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:53
S37	55	(encapsulation with "solder mask") and @ad<"20020722" not micron. as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:54

S38	51	(((("3838984") or ("5045921") or ("5409865") or ("5420460") or ("5600180") or ("5604379") or ("5608265") or ("5616958") or ("5640047") or ("5650593") or ("5656863") or ("5663593") or ("5663594") or ("5672912") or ("5859475") or ("5270267") or ("5677566") or ("5715593") or ("5785538") or ("5821605") or ("5863805") or ("5879964") or ("5880520") or ("5900582") or ("5904500") or ("5907186") or ("5929514") or ("5933708") or ("5951804") or ("5998865") or ("6013109") or ("6013535") or ("6020692") or ("6028356") or ("6107683") or ("6127833") or ("6143581") or ("6166443") or ("6169329") or ("6204093") or ("6210992") or ("5849608") or ("5920118") or ("6181569") or ("6287893") or ("6326698") or ("6376279") or ("6165885") or ("6245594") or ("6426241") or ("6284566") or ("6359221") or ("6441483") or ("6465734") or ("6475629") or ("6507107") or ("6514847") or ("6538309") or ("6555923") or ("6573612") or ("6577004") or ("6590297") or ("6671951") or ("6432746") or ("6577015") or ("6630730") or ("6653173") or ("6664139")).PN.) not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 14:00
S39	32722	hitachi.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 08:34
S40	60	yaguchi.in. and hitachi.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 08:34
S41	3656	resin adj plate	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 10:26
S42	2904	solder adj mask	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 10:26
S43	8	(resin adj plate) and (solder adj mask)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 10:27
S44	7464	transfer adj molding	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 11:02

S45	325	(transfer adj molding) and needle	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 11:02
S46	29	((transfer adj molding) and needle) and dispenser	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 11:02
S47	4	(((transfer adj molding) and needle) and dispenser) and encapsulant	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S48	4	(((transfer adj molding) and needle) and dispenser) and encapsulant	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S49	4803	((((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722") not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 14:52
S50	152	((((((transfer adj molding) and needle) and dispenser) and encapsulant) (((((438/118,127) or (257/737,738,782,783,787)). CCLS.) and @ad<"20020722") not micron.as.)) and @pd>"20040120"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/11/05 08:40
S51	0	10/370755	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:24
S52	0	10/672098	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:24
S53	1	09/590527	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:41
S54	1	"09590621"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:39
S55	2	10/191424	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S56	1	10/641471	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S57	1	10/642908	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S58	4	((("5181984") or ("6150193") or ("6469897") or ("6479887")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/01 10:41

S59	11	(("5196371") or ("6593220") or ("5181984") or ("6150193") or ("6469897") or ("6479887") or ("20040005770") or ("20040165362") or ("20040032020") or ("20040077109") or ("20040142058")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/02 13:15
S60	64	(((((transfer adj molding) and needle) and dispenser) and encapsulant.) (((((438/118,127) or (257/737,738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.)) and @pd>"20041109"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 13:18
S61	7	(("6017776") or ("6048755") or ("6049129") or ("6177723") or ("6214645") or ("6246124") or ("6329224")).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 14:52